Special Issue

Biomedical Engineering Advances for Medical and Pharmaceutical Applications

Message from the Guest Editor

This Special Issue aims to gather original peer-reviewed research and review articles featuring important and recent developments or achievements in biomedical engineering research, with an emphasis on medical and pharmaceutical applications. Authors who are well-known experts in their domain are invited to submit their contribution at any time until the end of April 2023. Papers can cover either the experimental or theoretical aspect, or both aspects, of biomedical engineering, especially tissue engineering, cell engineering, developmental engineering, organoids, and lab-, organ-, and organoid-on-a-chip.

- tissue engineering
- cell engineering
- regenerative medicine
- developmental engineering
- microfluidics
- lab-on-a-chip
- organ-on-a-chip
- organoid-on-a-chip
- biomedical engineering
- biomaterials

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Deadline for manuscript submissions

closed (20 August 2023)

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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